PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): James S. Raitter

Patent No.: 6,792,365 B2

Issued: September 14, 2004

For: SEQUENTIAL UNIQUE MARKING

Attorney Docket No.: 2269-4539US

VIA ELECTRONIC FILING

September 6, 2007

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT OFFICE MISTAKES (37 C.F.R. § 1.322)

Attn.: Certificate of Corrections Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

It is noted that several errors appear in this patent of a typographical nature. These errors are due to mistakes in printing on the part of the U.S. Patent and Trademark Office, and occurred through no fault of the Applicant. A certificate of correction in the form attached hereto is requested.

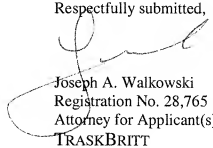
Please note that an Amendment Pursuant to 37 C.F.R. § 1.312(a) (copy enclosed) was filed concurrently with the issue fee on May 17, 2004, but the amendments contained therein were apparently not completely included in the printed patent. Attached is a copy of the previously filed Amendment Pursuant to 37 C.F.R. § 1.312(a) and the date-stamped postcard, acknowledging receipt by the PTO, to provide proof of such filing. The subject matter of this amendment is included in the attached Certificate of Correction.

Please send the Certificate to:

Name: Joseph A. Walkowski
Address: TraskBritt
P.O. Box 2550
Salt Lake City, Utah 84110

Attached hereto is Form PTO/SB/44, which is suitable for printing.

Respectfully submitted,



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Date: September 6, 2007
JAW/csw

Attachments: PTO/SB/44
copy of Amendment Pursuant to 37 C.F.R. § 1.312(a)
copy of date-stamped postcard

Document in ProLaw

PTO/SB/44 (08-07)
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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO : 6,792,365 B2
APPLICATION NO.: 09/928,032
ISSUE DATE : September 14, 2004
INVENTOR(S) : James S. Raitter

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page:

In ITEM (57) "Abstract"	3rd LINE,	change "of devices" to --of semiconductor devices--
	8th LINE,	change "each device" to --each semiconductor device-- and change "of devices" to --of semiconductor devices--
	9th LINE,	change "device with the data" to --semiconductor device with the data.--

In the specification:

COLUMN 3,	LINE 57,	change "(i.e., 1.0,2.0,3.0)" to --(i.e., 1.0, 2.0, 3.0)--
COLUMN 4,	LINE 4,	change "IC's," to --ICs,--
COLUMN 4,	LINE 5,	change both occurrences of "IC's," to --ICs,--
COLUMN 4,	LINE 6,	change "IC's," to --ICs,-- and change "(SIMM's)," to --(SIMMs),--
COLUMN 4,	LINE 7,	change "(DIMM's)," to --(DIMMs),--
COLUMN 4,	LINE 8,	change "(MCM's)." to --(MCMs).--

MAILING ADDRESS OF SENDER (Please do not use customer number below):

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Salt Lake City, Utah 84102 USA

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PATENT NO : 6,792,365 B2
APPLICATION NO.: 09/928,032
ISSUE DATE : September 14, 2004
INVENTOR(S) : James S. Raitter

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the claims:

CLAIM 1, COLUMN 5, LINE 44, change "device with" to --device of said plurality with--

CLAIM 1, COLUMN 5, LINES 36-44, change the format of Claim 1 as follows:

1. A method of unique sequential marking a plurality of semiconductor devices in a multi-die handling device comprising:
   reading an ID code on said multi-die handling device;
   retrieving a tray map file corresponding to said ID code;
   determining a tray matrix of said multi-die handling device;
   retrieving data from the tray map file, said data comprising unique characters correlating to each semiconductor device of said plurality of semiconductor devices; and
   marking each semiconductor device of said plurality with said data.

CLAIM 4, COLUMN 5, LINE 52, change "device comprises" to --device of said plurality comprises--

CLAIM 5, COLUMN 5, LINE 54, change "wherein said" to --wherein each--

CLAIM 5, COLUMN 5, LINE 55, change "device each comprise" to --device of said plurality comprises--

CLAIM 8, COLUMN 6, LINE 2, change "device." to --device of said plurality.--

CLAIM 9, COLUMN 6, LINE 4, change "device." to --device of said plurality.--

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UNITED STATES PATENT AND TRADEMARK OFFICE
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PATENT NO : 6,792,365 B2
APPLICATION NO.: 09/928,032
ISSUE DATE : September 14, 2004
INVENTOR(S) : James S. Raitter

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the claims (continued):

CLAIM 10,	COLUMN 6,	LINE 9,	change “pocket of said” to --pocket of said plurality of pockets of said--
CLAIM 14,	COLUMN 6,	LINE 29,	change “wherein said” to --wherein said at least one--
CLAIM 14,	COLUMN 6,	LINE 30,	change “device each comprise” to --device comprises--
CLAIM 19	COLUMN 6,	LINE 59,	change “device;” to --device of said plurality;--
CLAIM 19	COLUMN 6,	LINE 61,	change “device;” to --device of said plurality;--
CLAIM 19	COLUMN 6,	LINE 63,	change “carrier;” to --carrier of said plurality;--
CLAIM 19	COLUMN 6,	LINE 64,	change “carrier;” to --carrier of said plurality;--
CLAIM 19	COLUMN 6,	LINE 66,	change “carrier;” to --carrier of said plurality;--
CLAIM 20,	COLUMN 7,	LINE 5,	change “wherein said” to --wherein said at least one--
CLAIM 20,	COLUMN 7,	LINE 6,	change “carrier is” to --carrier of said plurality of carriers is--
CLAIM 24,	COLUMN 7,	LINE 16	change “semiconductor device each comprise” to --plurality of semiconductor devices each comprises--
CLAIM 25,	COLUMN 7,	LINE 25,	change “device.” to --device of said plurality.--
CLAIM 26,	COLUMN 7,	LINE 27,	change “device.” to --device of said plurality.--
CLAIM 27,	COLUMN 7,	LINE 32,	change “carrier having” to --carrier of said plurality having--
CLAIM 27,	COLUMN 8,	LINE 1,	change “device;” to --device of said plurality;--
CLAIM 27,	COLUMN 8,	LINE 3,	change “device;” to --device of said plurality;--
CLAIM 27,	COLUMN 8,	LINE 5,	change “carrier;” to --carrier of said plurality;--
CLAIM 27,	COLUMN 8,	LINE 6,	change “a carrier;” to --each carrier of said plurality;--
CLAIM 27,	COLUMN 8,	LINE 9,	change “the carrier;” to --each carrier of said plurality;--

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO : 6,792,365 B2
APPLICATION NO.: 09/928,032
ISSUE DATE : September 14, 2004
INVENTOR(S) : James S. Raitter

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the claims (continued):

CLAIM 28,	COLUMN 8,	LINE 15,	change “wherein said” to --wherein each--
CLAIM 28,	COLUMN 8,	LINE 16,	change “carrier comprises” to --carrier of said plurality comprises--
CLAIM 32,	COLUMN 8,	LINE 25,	change “wherein said” to --wherein each--
CLAIM 32,	COLUMN 8,	LINE 26,	change “device each comprise” to --device of said plurality comprises--
CLAIM 33,	COLUMN 8,	LINE 35,	change “device.” to --device of said plurality.--
CLAIM 34,	COLUMN 8,	LINE 37,	change “device.” to --device of said plurality.--

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THE P[illegible]NT & TRADEMARK OFFICE MAILROOM DA[illegible]N THIS S
STAMPED HEREON IS AN ACKNOWLEDGEMENT THA[illegible]
DATE THE PATENT & TRADEMARK OFFICE RECEIVED:

Transmittal Letter (2 pages, in duplicate); Part B - Issue Fee Transmittal (1
page); Check No. 20260 in the amount of $1,645.00; Amendment
Pursuant to 37 C.F.R. § 1.312(a) (12 pages); Comments on Statement of
Reasons for Allowance (3 pages); and Fee Addressee for Receipt of PTO
Notices Relating to Maintenance Fees (2 pages)

Invention:	SEQUENTIAL UNIQUE MARKING
Applicant(s):	James S. Raitter
Filing Date:	August 10, 2001
Serial No.:	09/928,032
Date Sent:	May 17, 2004 via Express Mail Label No. EV325774384US
Docket No.:	2269-4539US

JMM/ps:rh

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

James S. Raitter

Serial No.: 09/928,032

Filed: August 10, 2001

For: SEQUENTIAL UNIQUE MARKING

Confirmation No.: 5192

Examiner: M. Charioui

Group Art Unit: 2857

Attorney Docket No.: 2269-4539US
(MUEI-0560.00/US)

Notice of Allowance Mailed:

February 17, 2004

Express Mail Mailing Label No.: EV 325774384 US

Date of Deposit with USPS: May 17, 2004

Person making Deposit: Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 12 of this paper.

IN THE SPECIFICATION:

Please replace paragraph number **[0013]** with the following rewritten paragraph:

[0013] Another embodiment of the present invention includes a method of culling semiconductor devices or bare semiconductor dice from a reject bin. The method includes retrieving a plurality of semiconductor devices or bare semiconductor dice from a reject bin, providing a plurality of multi-die handling devices having a plurality of pocket locations and assigning each ~~multi-die~~ multi-die handling device an ID code. Each semiconductor device or bare semiconductor die is placed in a pocket location of the plurality of pocket locations. The semiconductor devices or bare semiconductor dice are tested and a tray map file comprising test data is generated. The tray map file is stored in association with the ID code of the multi-die handling device. The method further includes reading the ID code on a multi-die handling device, retrieving the tray map file corresponding to the ID code, determining a tray matrix of the multi-die handling device, retrieving unique test data from the tray map file and marking each semiconductor device or bare semiconductor die of said plurality of semiconductor devices or bare semiconductor dice with the corresponding test data.

Please replace paragraph number **[0018]** with the following rewritten paragraph:

[0018] As shown in drawing FIG. 1, a JEDEC tray 100 consists of pocket locations 110 in rows and columns (X and Y-axis coordinates). Each pocket location 110 is assigned a unique coordinate number based on its X and Y-axis coordinates. In the example shown, pocket locations 110 receive a unique whole number (*i.e.,* 1.0, 2.0, 3.0) corresponding to its location along the X axis and a unique fractional number (*i.e.*, 0.1, 0.2, 0.3) corresponding to its location along the Y axis. While the current invention is described using a JEDEC tray 100, it will be understood by those of skill in the art that the invention is applicable to any multi-die handling device including multi-die handling devices having vertical carrier capabilities (*e.g.,* a multi-die handling device that can store dice along X, Y and Z coordinates). Further, as used herein, the terms "tray," "carrier" and ~~"multi-die~~ "multi-die handling device" are used interchangeably.

Please replace paragraph number **[0019]** with the following rewritten paragraph:

[0019] It will be further understood by those having skill in the field of this invention that the present invention is applicable to any IC device, including Dynamic Random Access Memory (DRAM) ~~IC's,~~ ICs, Static Random Access Memory (SRAM) ~~IC's,~~ ICs, Synchronous DRAM (SDRAM) ~~IC's,~~ ICs, processor ~~IC's,~~ ICs, Single In-Line Memory Modules ~~(SIMM's),~~ (SIMMs), Dual In-Line Memory Modules ~~(DIMM's),~~ (DIMMs), and other Multi-Chip Modules ~~(MCM's).~~ (MCMs).

IN THE CLAIMS:

Claims 1, 6-11, 15-18, 24, 27, 28, and 32-34 have been amended herein. All of the pending claims 1 through 34 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently amended) A method of unique sequential marking a plurality of semiconductor devices in a multi-die handling device comprising:
reading an ID code on said multi-die handling device;
retrieving a tray map file corresponding to said ID code;
determining a tray matrix of said multi-die handling device;
retrieving data from the tray map file, said data comprising unique characters correlating to each semiconductor device of said plurality of semiconductor devices; and
marking each semiconductor device of said plurality with said data.

2. (Original) The method according to claim 1, wherein said multi-die handling device comprises a JEDEC tray.

3. (Original) The method according to claim 1, wherein said data further comprises non-unique characters.

4. (Original) The method according to claim 3, wherein said non-unique characters are selected from the group consisting of semiconductor device data, date code, country code and company logo.

5. (Original) The method according to claim 1, wherein said unique characters comprise test data extracted for at least one semiconductor device from the tray map file.

6. (Currently amended) The method according to claim 1, wherein each semiconductor device of said plurality comprises an integrated circuit semiconductor device.

7. (Currently amended) The method according to claim 6, wherein ~~said~~ each semiconductor device ~~each comprise~~ of said plurality comprises a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules (SIMMs), and Dual In-Line Memory Modules (DIMMs).

8. (Currently amended) The method of claim 1, wherein marking occurs before packaging each semiconductor device of said plurality.

9. (Currently amended) The method of claim 1, wherein marking occurs after packaging each semiconductor device of said plurality.

10. (Currently amended) A method of culling semiconductor devices from a reject bin, said method comprising:

retrieving a plurality of semiconductor devices from at least one reject bin;

providing at least one carrier of a plurality of carriers having a plurality of pocket locations;

assigning said at least one carrier of said plurality of carriers an ID code;

placing each semiconductor device of said plurality of semiconductor devices in a pocket location of said plurality of pocket locations;

testing each semiconductor device of said plurality;

generating a tray map file comprising test data corresponding to each semiconductor device of said plurality;

storing the tray map file in association with the ID code of said at least one carrier of said plurality;

reading the ID code on said at least one carrier of said plurality;

retrieving the tray map file corresponding to said ID code;

determining a tray matrix of said at least one carrier of said plurality;

retrieving test data from the tray map file; and

marking each semiconductor device of said plurality of semiconductor devices with the corresponding test data.

11. (Currently amended) The method according to claim 10, wherein said at least one carrier of said plurality of carriers is a multi-die handling device.

12. (Original) The method according to claim 11, wherein said multi-die handling device comprises a JEDEC tray.

13. (Original) The method according to claim 10, wherein said test data comprises non-unique characters.

14. (Original) The method according to claim 13, wherein said non-unique characters comprise non-unique characters selected from the group consisting of semiconductor device data, date code, country code and company logo.

15. (Currently amended) The method according to claim 10, wherein said plurality of semiconductor ~~device~~ devices each ~~comprise~~ comprises a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules (SIMMs) and Dual In-Line Memory Modules (DIMMs).

16. (Currently amended) The method of claim 10, wherein marking occurs before packaging each semiconductor device of said plurality.

17. (Currently amended) The method of claim 10, wherein marking occurs after packaging each semiconductor device of said plurality.

18. (Currently amended) A method of unique sequential marking comprising:
providing a multi-die handling device having a plurality of pockets therein in a matrix;
placing at least one semiconductor device in at least one pocket of said plurality of pockets of said multi-die handling device;
reading an ID code on said multi-die handling device;
retrieving a tray map file corresponding to said ID code;
determining a tray matrix of said multi-die handling device;
retrieving data from the tray map file, said data comprising unique characters correlating to said at least one semiconductor device; and
marking said at least one semiconductor device with said data.

19. (Original) The method according to claim 18, wherein said multi-die handling device comprises a JEDEC tray.

20. (Original) The method according to claim 18, wherein said data further comprises non-unique characters.

21. (Original) The method according to claim 20, wherein said non-unique characters comprise non-unique characters selected from the group consisting of semiconductor device data, date code, country code and company logo.

22. (Previously presented) The method according to claim 18, wherein said unique characters comprise test data extracted from said tray map file.

23. (Previously presented) The method according to claim 18, wherein said at least one semiconductor device is an integrated circuit semiconductor device.

24. (Currently amended) The method according to claim 23, wherein said at least one semiconductor device ~~each comprise~~ comprises a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules (SIMMs), and Dual In-Line Memory Modules (DIMMs).

25. (Previously presented) The method of claim 18, wherein marking occurs before packaging said at least one semiconductor device.

26. (Previously presented) The method of claim 18, wherein marking occurs after packaging said at least one semiconductor device.

27. (Currently amended) A method of culling semiconductor devices from a reject bin, said method comprising:

retrieving a plurality of semiconductor devices from a reject bin;

providing a plurality of carriers, each carrier of said plurality having a plurality of pocket locations in a tray matrix;

assigning each carrier of said plurality of carriers an ID code;

placing each semiconductor device of said plurality of semiconductor devices in a pocket location of said plurality of pocket locations;

testing each semiconductor device of said plurality;

generating a tray map file comprising test data corresponding to each semiconductor device of said plurality;

storing the tray map file in association with the ID code of each carrier of said plurality;

reading the ID code on ~~a carrier~~ each carrier of said plurality;

retrieving the tray map file corresponding to said ID code;

determining a tray matrix of ~~the~~ each carrier of said plurality;

retrieving test data from the tray map file; and

marking each semiconductor device of said plurality of semiconductor devices with the corresponding test data.

28. (Currently amended) The method according to claim 27, wherein ~~said~~ each carrier of said plurality comprises a multi-die handling device.

29. (Original) The method according to claim 28, wherein said multi-die handling device comprises a JEDEC tray.

30. (Original) The method according to claim 27, wherein said test data comprises non-unique characters.

31. (Original) The method according to claim 30, wherein said non-unique characters comprise non-unique characters selected from the group consisting of semiconductor device data, date code, country code and company logo.

32. (Currently amended) The method according to claim 27, wherein ~~said~~ each semiconductor device ~~each comprise~~ of said plurality comprises a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules (SIMMs), and Dual In-Line Memory Modules (DIMMs).

33. (Currently amended) The method of claim 27, wherein marking occurs before packaging each semiconductor device of said plurality.

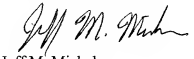
34. (Currently amended) The method of claim 27, wherein marking occurs after packaging each semiconductor device of said plurality.

REMARKS

This amendment corrects errors in the text. Entry is respectfully solicited.

This amendment is submitted prior to or concurrently with the payment of the issue fee and, therefore, no petition or fee is required. No new matter has been added.

Respectfully submitted,



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Date: May 17, 2004
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